onsemi

Ambient Light Sensor, Linear Current Output, with 2-Stage Gain Switching

LA0151CS

Overview

The LA0151CS is a photo IC for ultra-small package ambient light sensor. It enables to be mounted on a very small limited space such as on the mobile phones which is becoming small and thinner and on other mobile applications.

Features

- Linear Current Output
- Low Gain Mode Function [Low Gain: -35 dB]

Typical Applications

- Mobile Phones and Tablets
- Digital Still Cameras
- Security Camera

SPECIFICATION

ABSOLUTE MAXIMUM RATINGS (at Ta = 25°C)

Parameter	Symbol	Conditions	Rating	Unit
Maximum Supply Voltage	V _{CC}		6	V
Operating Temperature	Topr		-30 to +85	°C
Storage Temperature	Tstg		-40 to +100	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

RECOMMENED OPERATING CONDITIONS AND OPERATING VOLTAGE RANGE (at Ta = 25°C)

			Rating			
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Recommended Supply Voltage	V _{CC}		2.2	3.3	5.5	V
SW Pin Low Voltage	VI	Normal gain mode	0	-	0.4	V
SW Pin High Voltage	Vh	Low gain mode	2.1	-	-	V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.



ORDERING INFORMATION

0	rdering Code	Package	Shipping [†]
LAC	151CS-TLM-E	ODCSP4 (Pb–Free / Halogen Free	5000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

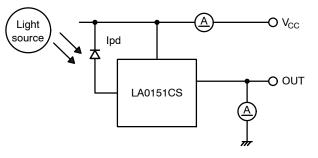
ELECTRICAL CHARACTERISTICS (at Ta = 25° C, V_{CC} = 3.3 V)

			Ratings			
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Current Dissipation (1) (Note 2, 4)	I _{CC}	Ev = 1000 lx, R_L = 5 k Ω , N mode	90	150	210	μΑ
Current Dissipation (2) (Note 2, 4)	I _{CC}	Ev = 1000 lx, R_L = 5 k Ω , L mode	42	70	98	μΑ
Output Current (1) (Note 2, 4)	l _O 1	Ev = 100 lx, N mode	6	8	10	μΑ
Output Current (2) (Note 2, 4)	I _O 2	Ev = 1000 lx, N mode	60	80	100	μΑ
Output Current (3) (Note 2, 4)	I _O 3	Ev = 100 lx, L mode	0.12	0.16	0.2	μΑ
Output Current (4) (Note 2, 4)	I _O 4	Ev = 1000 lx, L mode	1.2	1.6	2.0	μΑ
Dark Current	lleak	Ev = 0 lx, N mode, L mode	-	-	0.1	μΑ
Temperature Coefficient (Note 3)	ltc	Ev = 100 lx, N mode, L mode, Ta = -20 to 60°C	-	0.34	_	%/°C
Rise Time (1) (Note 5)	Tr1	Ev = 1000 lx, R_L = 5 k Ω , N mode	-	15	40	μs
Rise Time (2) (Note 5)	Tr2	Ev = 1000 lx, R_L = 500 k Ω , L mode	-	20	50	μs
Fall Time (1) (Note 5)	Tf1	Ev = 1000 lx, R_L = 5 k Ω , N mode	-	150	500	μs
Fall Time (2) (Note 5)	Tf2	Ev = 1000 lx, R_L = 500 k Ω , L mode	-	150	500	μs
Peak Sensitivity Wave Length (Note 3)	λр		-	550	-	nm
Saturation Output Voltage (Note 6)	Vo	Ev = 1000 lx, R_L = 150 k Ω , N mode	3.0	3.2	-	V

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

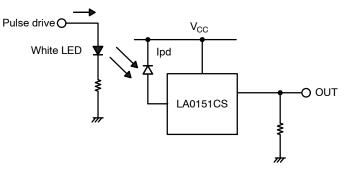
N mode and L mode stand for the normal gain mode and the low gain mode, respectively.
Measured with the standard light source A. White LED is used instead in the mass production line.

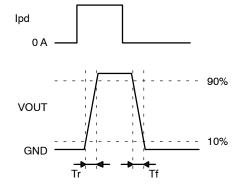
Design guaranteed item
Test circuit for measuring current dissipation and output current





5. Measuring method of rise time (Tr) and fall time (Tf)

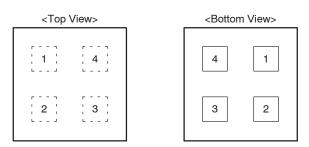






6. Reference value: min = 2.6 V and typ = 2.8 V when V_{CC} = 2.9 V

PAD LAYOUT



Pin No.	Pin Name Function	
1	V _{CC}	Power supply
2	SW	Switch
3	GND	Ground
4	OUT	Output

Ball pitch: 0.5 mm, Ball size: 0.18 mm \square

Figure 3. Pad Layout

PAD LAYOUT (Photos)

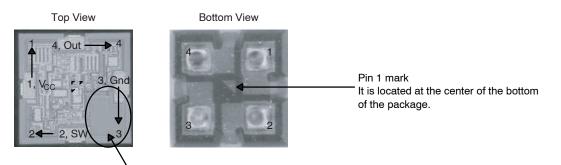
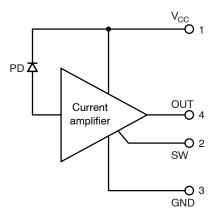


Photo diode. Only this part looks dark on the product.

*The photo diode is located in pin 3. Be careful not to mistake the pin 1 mark for the photo diode.

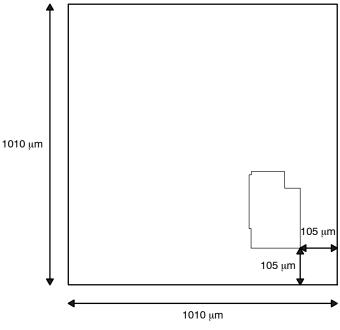
Figure 4. Pad Layout (Photos)



INTERNAL BLOCK DIAGRAM

Figure 5. Internal Block Diagram

CHIP PATTERN AND PHOTO-RECEIVING PATTERN DIAGRAMS



*Pin 1 is on the upper left.



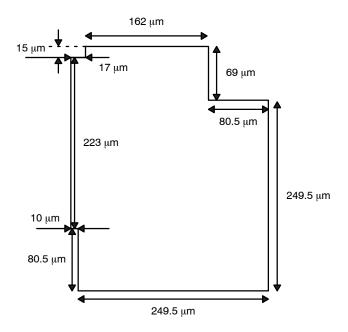
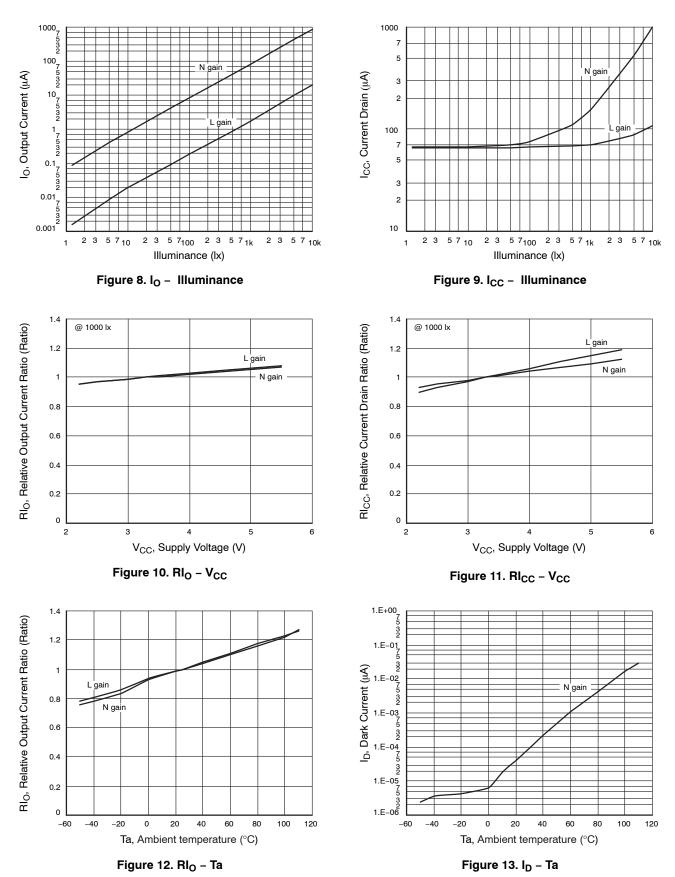


Figure 7. LA0151CS Photo-receiving Pattern Enlarged Diagram (Effective Area)



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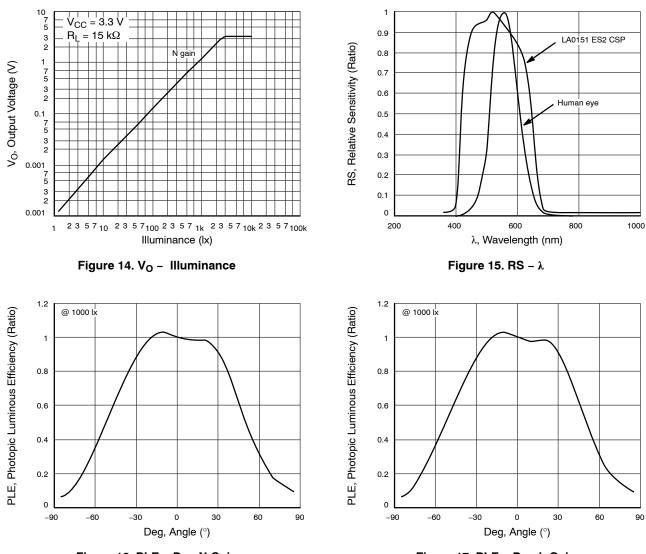


Figure 16. PLE – Deg N Gain

Figure 17. PLE – Deg L Gain

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



ODCSP4 1.01x1.01 CASE 570AC ISSUE O DATE 31 MAR 2012 BOTTOM VIEW TOP VIEW SIDE VIEW 1.01±0.07 3 4 3 4 □0,18±0,04 1.01±0.07 0.5 2 1 2 0.5 SIDE VIEW $\overleftarrow{4}$ (0, 5) MAX 9 0.67 0**.**1±0**.**04

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